

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

1. (Currently Amended) A cleaner that is an aqueous solution containing phosphoric acid, hydrofluoric acid, and ammonia and/or amine and having a pH ranging from 2 to ~~[[12]]~~ 6, wherein said aqueous solution contains:

0.5 to 25 mass% of phosphoric acid,

0.1 to 10 mass% of ammonia and/or amine, and

~~[[5×10⁻³]]~~ 0.1 to 5.0 mass% of hydrofluoric acid.

2. (Previously Presented) The cleaner according to claim 1, wherein the pH is regulated by phosphoric acid.

3. (Original) The cleaner according to claim 1 or 2, which further includes a surface active agent and/or a chelate agent.

4. (Previously Presented) The cleaner according to claim 1, which further includes hydrogen peroxide.

5. (Previously presented) The cleaner according to claim 1, which is used for cleaning off particles and/or metal impurities out of the surface of a semiconductor device substrate.

6. (Previously Presented) The cleaner according to claim 2, which further includes hydrogen peroxide.

7. (Previously Presented) The cleaner according to claim 3, which further includes hydrogen peroxide.

8. (Previously presented) The cleaner according to claim 2, which is used for cleaning off particles and/or metal impurities out of the surface of a semiconductor device substrate.

9. (Previously presented) The cleaner according to claim 3, which is used for cleaning off particles and/or metal impurities out of the surface of a semiconductor device substrate.

10. (Previously presented) The cleaner according to claim 4, which is used for cleaning off particles and/or metal impurities out of the surface of a semiconductor device substrate.